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(54) Title: METHOD FOR TRANSFERRING WAFERS AND RING

(57) Abstract

A method and installation are proposed with which a wafer is surrounded by a ring in a floating wafer reactor. This ring is used to restrict the change in temperature over the wafer, especially during introduction and removal. Moreover, such a ring can be used to position the wafer in the horizontal plane during the treatment. The wafer is not in contact with the ring during the treatment. The ring can optionally be provided with heating means.

